

## Invoice

Invoice No.190730211000



Ship From  
Seed Development Limited.  
  
Floor 4, Building 2,  
RunHengDingFeng Industrial Park,  
Liuxian Road 2, Bao'an District,  
Shenzhen 518055 China  
  
+86 755 33552591

**SHIP TO :**  
University of Malaya,Jannatul Naeem ,Leve  
l 3 Engineering Faculty of Engineering,Kual  
a Lumpur, 50603,WP KL, Malaysia  
0146215260

**BILL ADDRESS :**  
University of Malaya,Jannatul Naeem ,Leve  
l 3 Engineering Faculty of Engineering,Kual  
a Lumpur, 50603,WP KL, Malaysia  
0146215260

Date Ordered : 2019-07-30

Payment Method : Credit Card

Products	Model	Unit Price	Quantity	Total Price
Fusion PCB PCB Dimensions-65mm*55mm Impedance Control-No Surface Finish-HASL Minimum Solder Mask Dam-0.4mm† Copper Weight-1oz. Plated Half-holes / Castellated Holes-No Minimum Drill Hole Size-0.3mm PCB Color-Black Base Material-FR-4 TG130 No. of Layers-2 layers PCB Quantity-10 Blind or Buried Vias-No PCB Thickness-1.6 Trace Width / Spacing-6/6 mil No. of Different Designs-1 Expedited Option-No File-1201071_fes_duelchannel.rar	501010001	\$4.90	1	\$4.90
Sub-Total : DHL : Discount : Total :				\$4.90 \$18.51 \$0.00 \$23.41

